

ABSTRACT

There is provided a positive photosensitive composition which requires no burning, makes it possible to obtain necessary and sufficient
5 adhesion when it is applied under a humidity of 25 to 60%, makes it possible to carry out development with keeping high sensitivity while forming no residue, ensures sharp edges, can provide a very hard resist film and is improved in scratch resistance in the handling before development. The positive photosensitive composition comprises, (A) an alkali soluble organic
10 high molecular substance having a phenolic hydroxyl group, (B) a photo-thermal conversion material that absorbs infrared rays from an image exposure light source and converts it to heat, (C) at least one resin selected from the group consisting of: (1) vinylpyrrolidone/vinyl acetate copolymer and others, and (D) a dissolution inhibitor.